

ABSTRACT OF THE DISCLOSURE

A substrate structure for an integrated circuit package to be electrically connected to a printed circuit board. The substrate structure includes a plurality of lower metal sheets arranged in an array, a plurality of upper metal sheets arranged in an array, and an encapsulant for encapsulating the lower metal sheets and the upper metal sheets. Each of the lower metal sheets has an upper surface and a lower surface. Each of the upper metal sheets has an upper surface and a lower surface, and the lower surfaces of the upper metal sheets are stacked on the upper surfaces of the lower metal sheets. The upper surfaces of the upper metal sheets are exposed from the encapsulant, and the lower surfaces of the lower metal sheets are exposed from the encapsulant and electrically connected to the printed circuit board.